

Gudeng Precision Industrial Co. Ltd

家登精密工業股份有限公司



2023.4

Partner with **H.E.A.R.T.** , Grow with **P.A.S.S.I.ON.**

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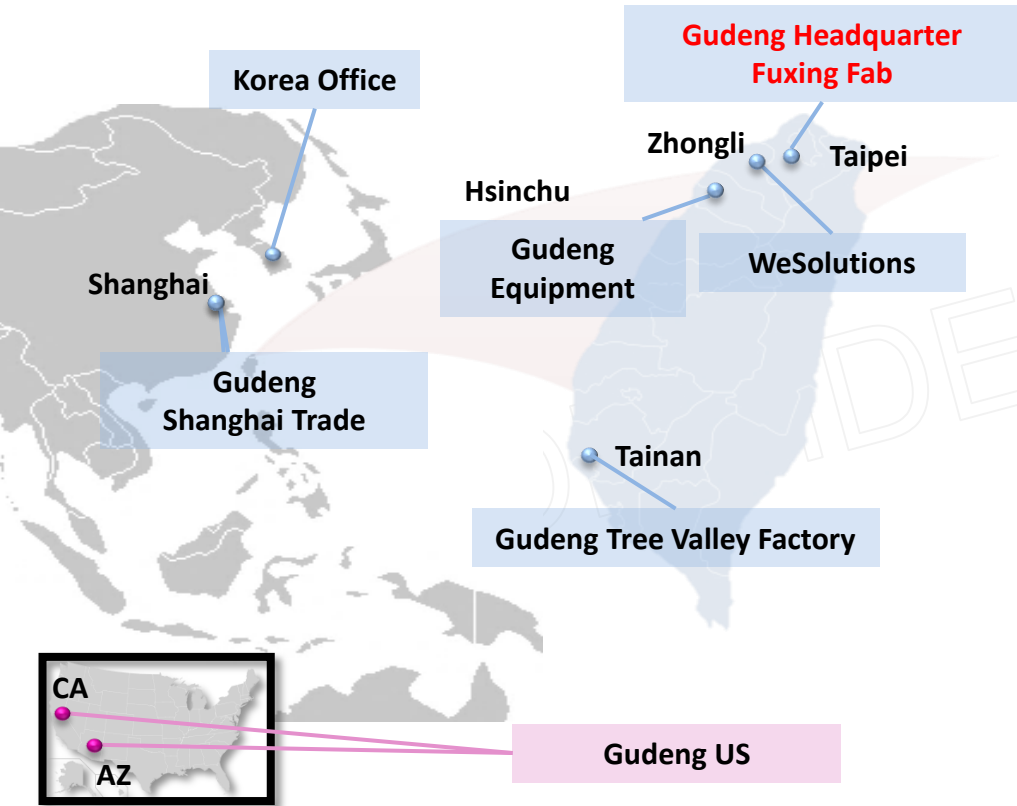
Safe Harbor Notice



This presentation includes forward-looking statements. Forward-looking statements refer to statement that address activities, events or developments that Gudeng Precision expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates, market share, total addressable market (TAM) and business plans).

Gudeng's forward-looking statements are subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements. Gudeng does not undertake any obligation to publicly update any forward-looking statement to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Gudeng Company Overview



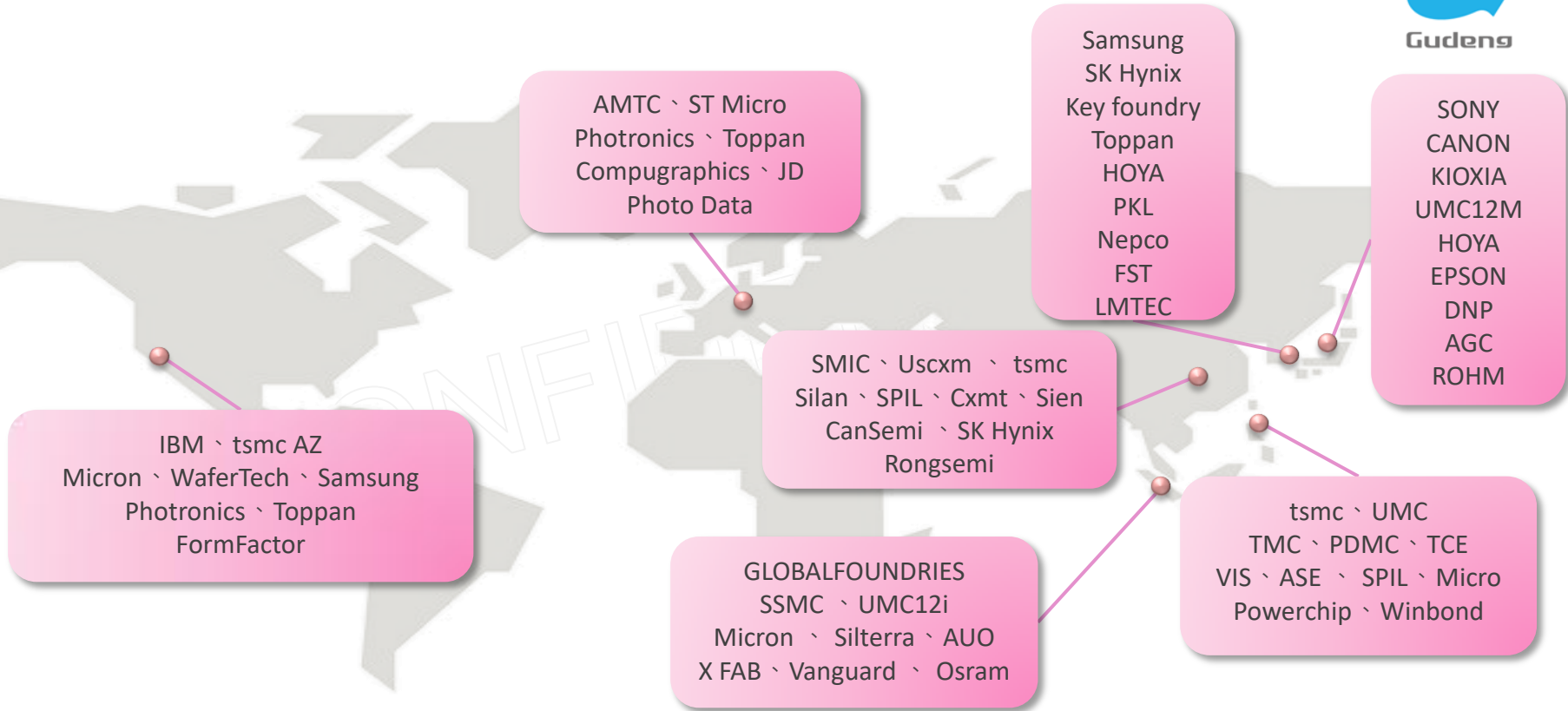
- ▶ Established : Mar. 20th , 1998
- ▶ Employee : **815**
- ▶ Capital : US\$ **28** million
- ▶ **2020** Group Revenue : US\$ **83** million
- ▶ **2021** Group Revenue : US\$ **104** million
- ▶ **2022** Group Revenue : US\$ **150** million
- ▶ Main Product :

Semiconductor

- Mask Handling Solutions
- Wafer Handling Solutions
- Equipment
- Other Service

Aerospace

Customers



Gudeng Total Solutions



Mask Carriers



Wafer Carriers



Logistic Automation Solutions



Product Application

	Product Design	Front End	OSAT/ Back end
	IC Design / Mask maker	Foundry/ IDM	Assembly/ Wafer sorting/ Final Test
Mask Carriers	V	V	V
Wafer Carriers		V	V
Automation	V	V	

Gudeng Total Solutions

Semiconductor Mature to Advanced Process

Gudeng Key Wafer Carriers

Process : 12" FOUP

Shipping : FOSB

Packaging : FP FOUP



Semiconductor Production Process

Product Design

Front End

Back End

Board Assembly

IC Design

Mask Maker

Foundry

Wafer Sort

Assembly

Final Test

Board Assembly

Board Testing

- Communication
- Automotive
- Consumer Electronics
- National Defense
- PC/NB

- Circuit Design
- Engineering Test

- Materials Fab
- Wafer Bank

- Wafer Bumping
- Wafer Probing

- Module, Board Assembly & Test



3D Advanced Packaging FP FOUP



- To continue the validity of Moore's Law, 3D advanced packaging technology has begun to enter a rapid growth
- 2021 3D packaging global capex will reach 11.9 billion US dollars, with a high growth rate in the next three years
- Gudeng is the first to develop 3D advanced packaging 510 FOUP, with market leadership and pricing power



- ❑ High-efficiency protection for 510x510 PCB during transportation and storage
- ❑ Maintain a clean environment with low humidity inside the FOUP, effectively reducing the risk of PCB contamination
- ❑ Compatible with AGV transportation

Market

Taiwan: tsmc 、 Unimicron 、 NanYa PCB 、 KINSUS
Overseas: INTEL 、 Ibsiden 、 Samsung 、 AT&S

Gudeng Revenue

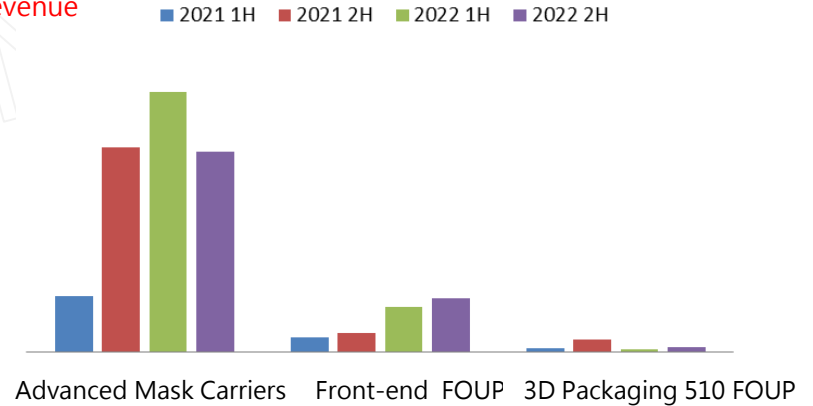


2022 Jan.~Dec. Key Product Revenue Performance :

Advanced Mask Carriers US\$ **52** million **50% of the carrier revenue**
 RSP Carriers US\$ **19** million **18% of the carrier revenue**
 FOUP US\$ **19** million **18% of the carrier revenue**

	2021 1H	2021 2H	2022 1H	2022 2H
Product	Revenue			
Advanced Mask Carriers	6,344,557	23,425,144	29,680,599	22,908,274
Front-end FOUP	1,643,997	2,092,293	5,084,396	6,172,400
3D Packaging PCB FOUP	392,933	1,394,900	226,100	470,204
Total	8,381,487	26,912,337	34,991,095	29,550,878

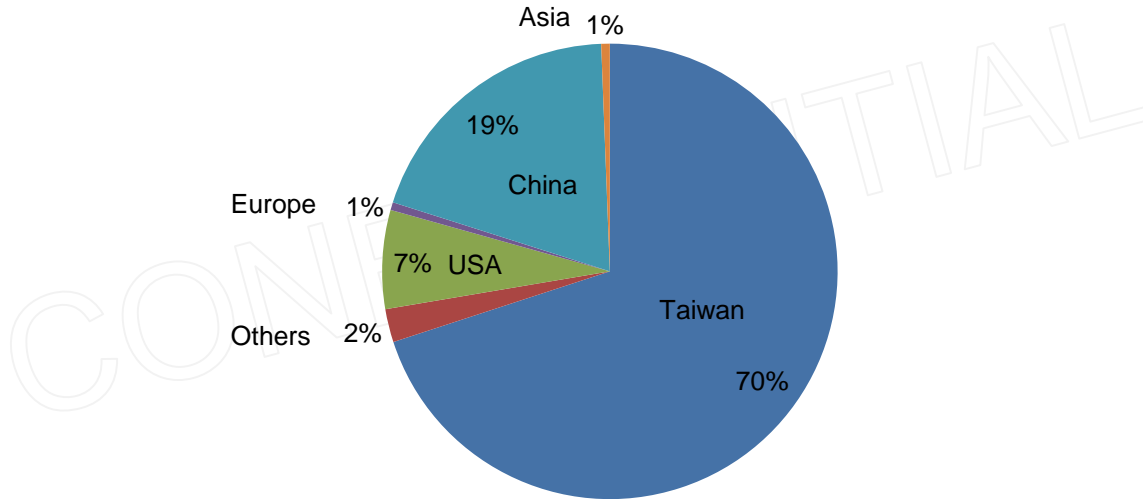
US dollars



Gudeng Revenue



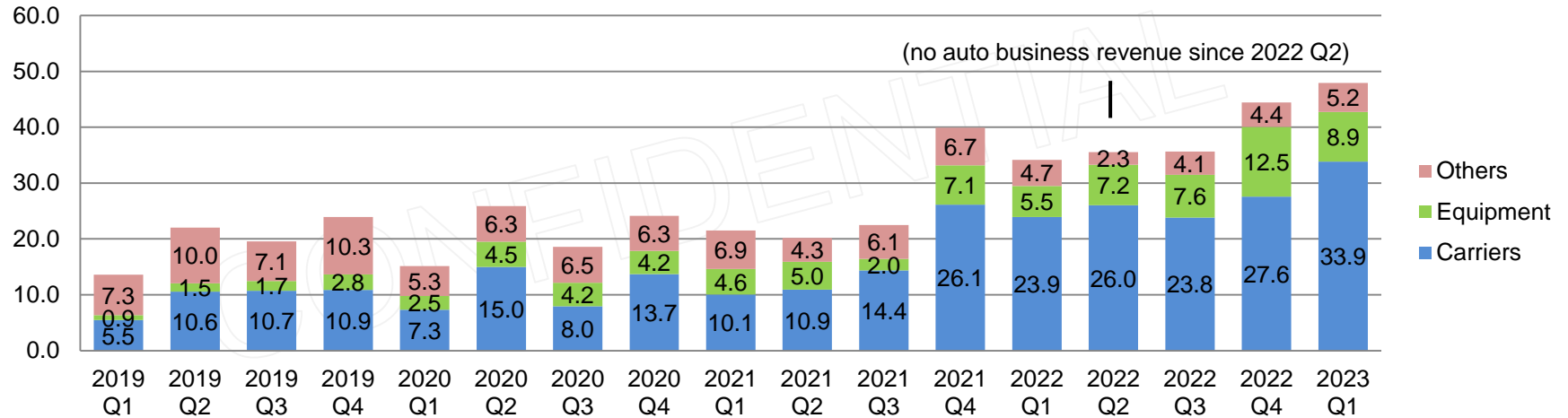
2022 Gudeng Revenue



Gudeng Revenue by quarter



Consolidated Revenue



US million dollars

2022 Feb. US \$9.2 million revenue including auto business about 0.5 million

2023 Feb. US \$14 million revenue with no auto business

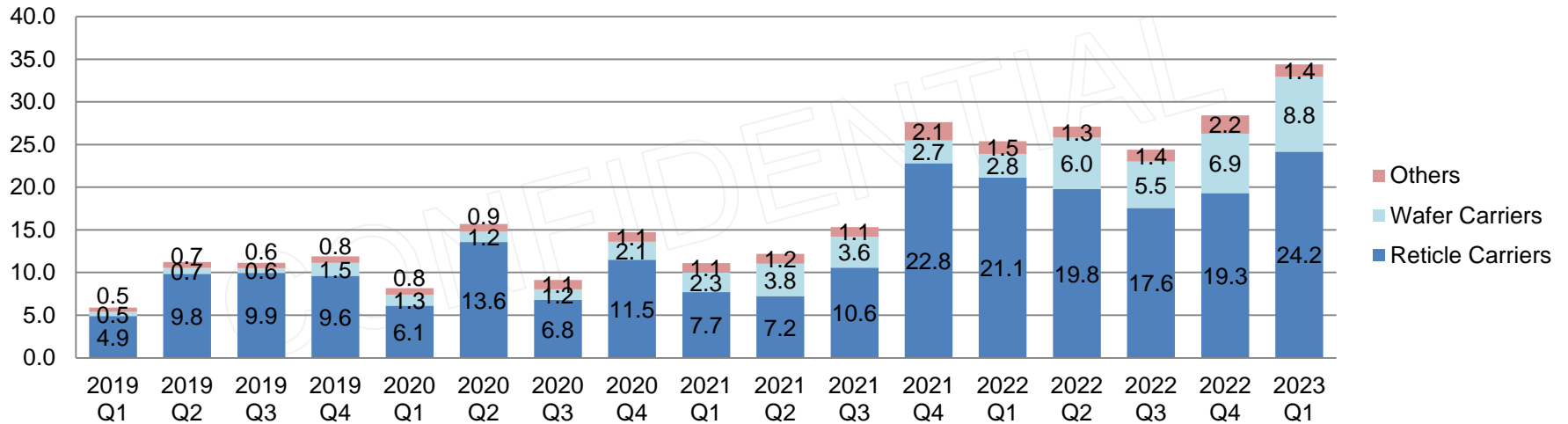
2022 Mar. US \$13.7 million revenue including auto business about 1 million

2023 Mar. US \$23.3 million revenue with no auto business

Gudeng Revenue by quarter



Core Business Revenue



US million dollars

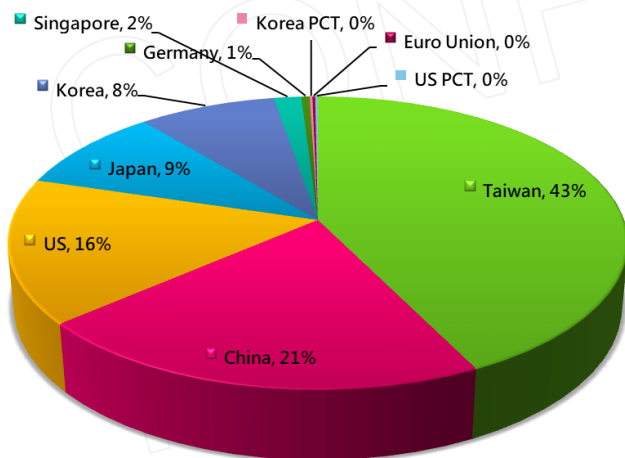
Gudeng Patents 、 R&D Expenses 、 Equipment Capex



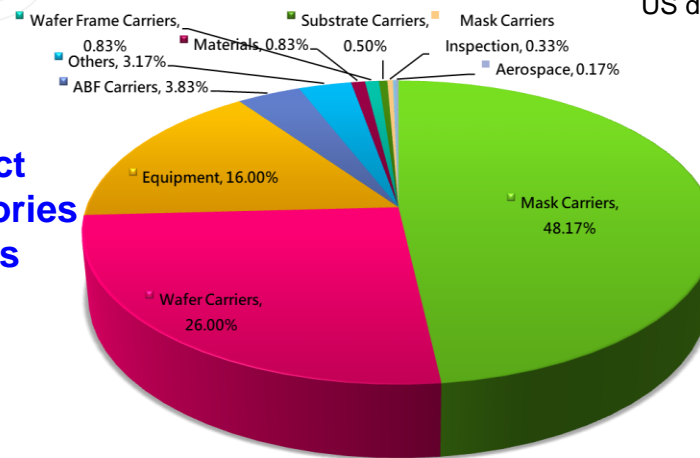
	2018	Revenue %	2019	Revenue %	2020	Revenue %	2021	Revenue %	2022	Revenue %
R&D Expenses	2,037,400	8.93%	2,806,333	6.94%	4,018,433	8.43%	4,880,733	7.34%	7,424,100	7.05%
Equipment Capex	2,006,333	8.80%	5,241,733	12.96%	19,820,833	41.58%	14,730,433	22.15%	25,299,966	24.02%

US dollars

Regional Patents

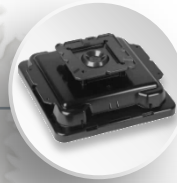


Product Categories Patents



As of Mar. 2023, 577 patents certificated Taiwan or abroad.

Gudeng Development Plan



Hi-NA EUV Worldwide Provider

- EUV Phase 2
- Smart Temperature & Vibration Detection



Mature Wafer Carriers

- FOSB
- Glass Box



Advanced Wafer Carriers

- Diffuser FOUF
- HD FOUF
- Frame Cassette
- 3D Packaging FOUF



New Material & Technology

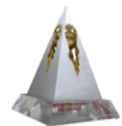
- **Equipment**
 - Carrier Cleaning
 - Stocker Solutions
- **Inspection**
 - VOC Inspection
- **Precise Machining**
 - Reticle Stage

Gudeng Core Competition



- Close relationship to customer
- Flexible manufacturing ability
- Rapid response toward customer needs
- 24-hours service for tier 1 customer
- With outstanding R&D talent
- Intensive training program for employees
- Project-base organization

	Gudeng	Competitor
Carriers Revenue	0.15 billion	0.85 billion
Carriers Profit	50%	21%
Stock Price	TPEX \$370	NASDAQ \$80



Gudeng ESG Performance



Management



2022 Revenue
US\$150 million

2022 EPS
11.12

Customer Satisfaction
80.82 score

CGV Ranking
2nd grade



TOP 100
High Value Enterprises List

Social

Salary Increase Rate **>9%**
better than industry



Charity Donation
US\$0.06 million

Medical Donation
US\$0.13 million

8 Industry-University
Cooperation Items



Environment

Annual Power Savings
55,604 kWh



Annual Water Savings
30,091 tons

Complete **RO Water**
System Project



Fully adopted
Hybrid Cars

Fabs
Smart Electric Meters

Homemade **Eco-Friendly Pallets**



Gudeng Strategies Overview



- Gudeng business covers the world and remains strong growth power
- China Market :
 - ◆ Reticle and wafer carriers 'market share continue to grow and take the place of other suppliers
 - ◆ Capacity is sufficient to support the entire China market
 - ◆ Accelerate the production base plan in China
- US Market :
 - ◆ Focus on advanced processes and aim to become single source of key customers
 - ◆ EUV, 3D packaging(Panel FOUP) shipments are steadily increasing
- Taiwan Market :
 - ◆ Following Taiwan major customer global plan, Gudeng has become its main global supplier
 - ◆ Wafer carriers certification completed by key customer, driving global customers to follow up
- Gudeng subsidiary – Gudeng Equipment, 2023 Q1 public release, 2024 IPO, will grow simultaneously with carriers
- Aerospace materials have completed verification and started shipping, with significant revenue in 2023 and double-speed growth in 2024



Thank You
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